

目次 INDEX

01	Company Profile	·· P.03
02	Financial Summary	·· P.10
03	Medium-Term Management Plan (2024 to 2026)	·· P.20
04	New Business (LE System)	·· P.29
05	Appendix	·· P.34

Company Profile

RS Technologies (RST) understood by the numbers;

Global Market Share
(Reclaimed Wafer)

World
No.1

Mond Market Share
(Reclaimed Wafer)

Operating Profit Margin (Consolidated Basis)

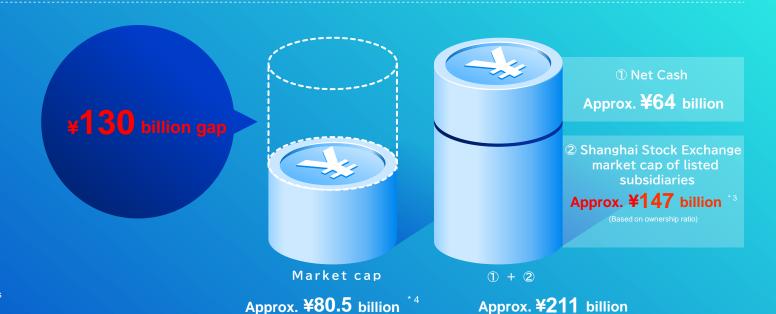
22.9%

Listed Markets
(Reclaimed Wafer and Prime Wafer Business)

2 Countries
*2

Corporate Valuation

While holding a plenty of assets, a significant divergence from market valuations exists



^{*1} Estimated by our company based on SEMI data

^{*2} Listed on the Tokyo Stock Exchange Prime Market and Shanghai Stock Exchange Departments

^{*3} Amount equivalent to our company's holdings (40%) of the average market capitalization of approximately 368 billion yen for the fiscal year ended December 2023

^{*4} Average market capitalization for the fiscal year ended December 2023

Company Profile



- Top company in the reclaimed wafer business with a global market share of 33% *1
- Entered the prime wafer business through a joint venture with a Chinese central company *2
- Expand business into areas where business synergies can be expected through M & A

Company name	RS Technologies, Co.,Ltd.			Registered Capital	RMB 1 billion
Establishment	December 10, 2010		GRINM Semiconductor Material Co., Ltd. GRITEK	Investment ratio	40.09% ^{*3}
Management Philosophy	"Respect the global environment, earn the trust of people, be creative and challenge ourselves"		(Beijing)	Listed	Shanghai Stock Exchange STAR market
Business Profile	 Reclaiming silicon wafers Manufacturing and sales of prime slicon wafers Manufacturing and sales of consumable materials for semiconductor manufacturing equipment 	Major Consolidated subsidiaries	RSTEC Semiconductor Taiwan Co., Ltd. (Taiwan)	Capital Investment ratio	NT \$300 million 100%
	 Sales of scanning acoustic tomograph (SAT) Sales of electronic components 		DG Technologies Co., Ltd.	Capital	100 million yen
Head office	NT Building 1-47-1 Ohi, Shinagawa-ku, Tokyo, JAPAN		(Japan)	ratio	100 76
Manufacturing Facilities	Miyagi, Ibaraki, Taiwan (Tainan), China (Dezhou)				
Capital	5,643 million yen (as of the end of December 2023)		Union Electronics Solutions Co., Ltd.	Capital	27 million yen
President and CEO	Nagayoshi Ho	(Japan)		Investment ratio	100%

^{*1} Estimated by our company based on SEMI data

^{*2} State-owned enterprises subject to management and supervision by the central government

^{*3} As of the end of December 2023

History



• Since its establishment, RST has firmly established itself as the world's leading company in the reclaimed wafer business. In 2018, RST became a comprehensive wafer manufacturer by making a major Chinese prime wafer manufacturer a consolidated subsidiary.

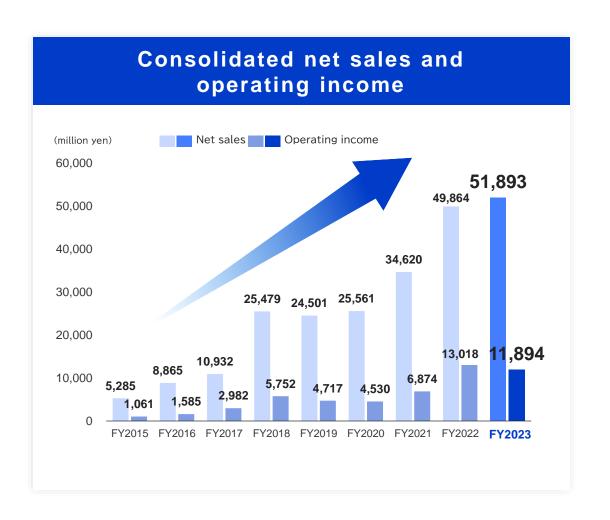
2010	Dec.	RS Technologies Co., Ltd. was established with the main business of reclaimed wafer.	Reclaimed
2014	Feb.	Established RSTEC Semiconductor Taiwan Co., Ltd. (consolidated subsidiary) in Taiwan	Reclaimed
2015	Mar.	Listed on Tokyo Stock Exchange "Mothers Market"	
2016	Sep.	RST transferred to "the First Section" of the Tokyo Stock Exchange	
2018	Jan.	Chinese prime wafer manufacturer, GRINM Semiconductor Material Co., Ltd. (GRITEK) became a consolidated subsidiary of RST	Prime
2018	May	Acquired 100% shares of Union Electronics Solution Co., Ltd.	Semi
2018	Aug.	Established Shandong GRIMN Semiconductor Materials Co., Ltd. (Shandong GRITEK), A consolidated subsidiary of GRITEK.	Prime
2019	Jan.	Acquired 100% shares of DG Technologies Co., Ltd.	Semi
2020	Feb.	Established Shanghai Union Semiconductor Co., Ltd. (Shanghai Union)	Semi
2022	Apr.	Transferred from the First Section of the Tokyo Stock Exchange to the "Prime Market" Establishment of Nomination and Compensation Committee	
2022	Nov.	GRITEK listed on Shanghai Stock Exchange (STAR market)	Prime
2023	Dec.	Established LE System Co.,Ltd, manufacturer of electrolyte for vanadium redox flow batteries (VRFB)	Energy

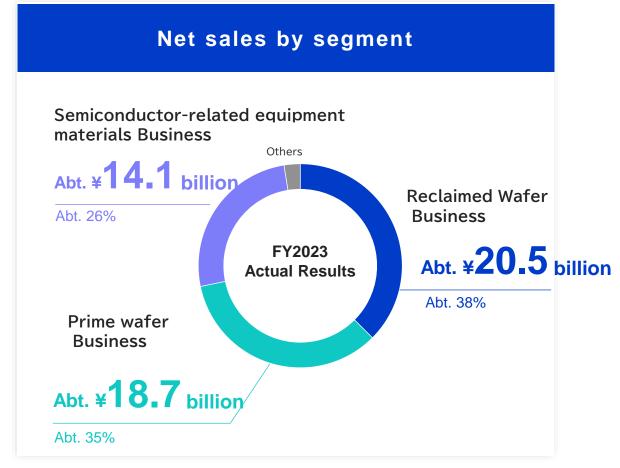


Current RS Technologies



- RST became comprehensive wafer manufacturers with the Reclaimed Wafer Business and Prime Wafer Business
- Expansion of business areas as Semiconductor-related equipment and materials Business
- No1 in global market share in reclaimed wafer business, and development of prime wafer business mainly in China

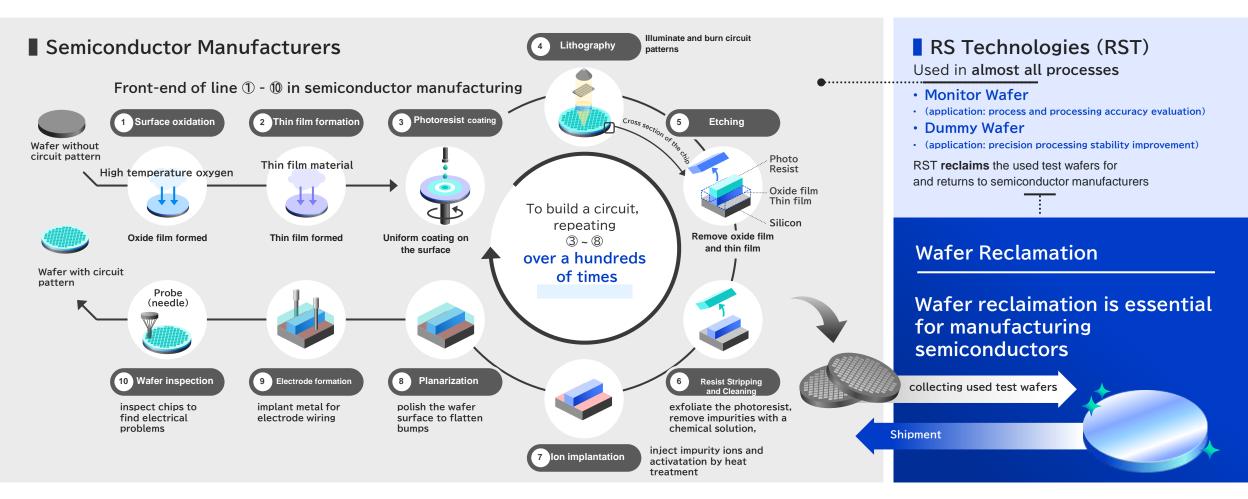




Business Profile (1/5 What Reclaimed Wafers is)



- Reclaimed wafers are wafers that have been reclaimed from test wafers used in the process of semiconductor manufacturing.
- Reclaimed wafers are used repeatedly by our customer. With our technology, RST can reclaim test wafers more than 10 times, helping to reduce costs for our customers, semiconductor manufacturers and executing eco-friendtly business model.



Business Profile (2/5 Reclaimed Wafer Business)



Achieve continued growth as a global supplier in the reclaimed wafer industry

Market Characte ristics

Continued growth in the semiconductor industry

The global semiconductor market size was 2023 to 2030 and grew at a CAGR of about 10% in 2030. It is projected to reach US \$1 trillion *1

*1 Source: "Semiconductor Market Forecast" by SEMI Japan

Resilient to economic fluctuations

- · Used by various applications such as the start-up of semiconductor manufacturing equipment
- When customers become more cost-conscious during a recession,

the amount of Reclaimed wafers' input increases

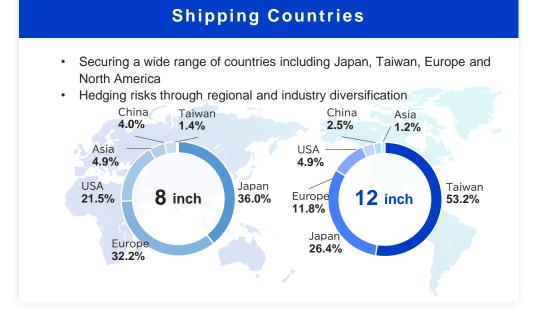
⇒ Less susceptible to the silicon cycle

The reclaimed wafer business is expcted to grow more in the future

Performance Trends (Reclaimed Wafer Business)

 Achieve significant growth by expanding production capacity and increasing the manufacturing sites



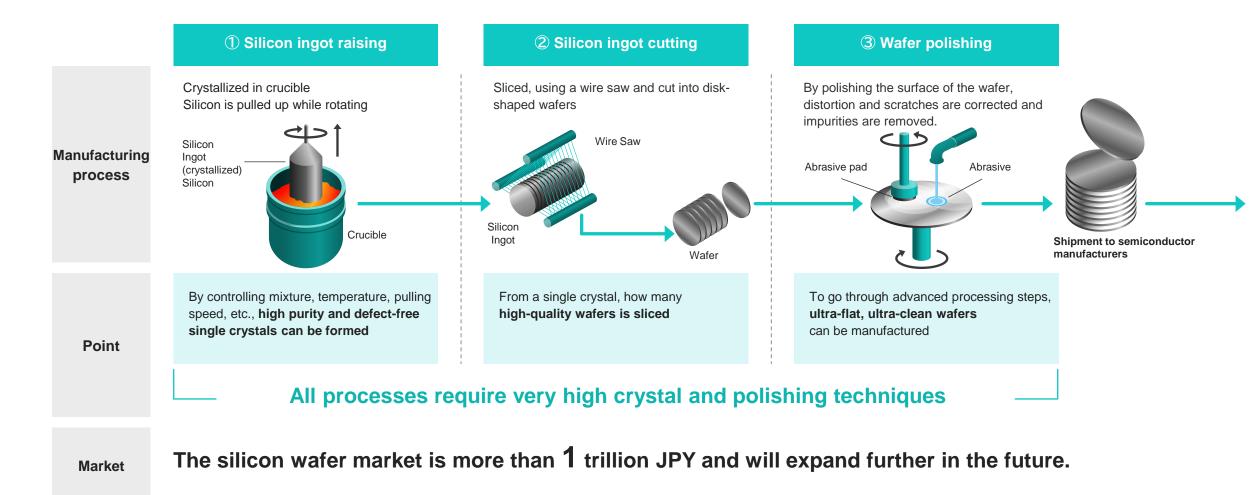


Results

Business Profile (3/5 Prime Wafer)



- A prime wafer is a silicon wafer that is a substrate material for semiconductors and used for semiconductor chips.
- Made from 99.99999999% silicon, it has the highest flatness of any material currently on Earth.



10

Business (4/5 Prime Wafer Business in RST)



- In 2018, the company entered the industry through a joint venture with China's largest state-owned research institute in the field of nonferrous metals, GRINM as a consolidated subsidiary, GRINM Semiconductor Material Co., Ltd.(GRITEK) * 1.
- Construction of a flagship plant for prime wafers in Shandong Province, China

Strengths of GRITEK

High Technological Capability

Poroviding high quality products in China through collaboration with GRINM



Business synergies with our core business

In polishing, cleaning and inspection, our know-how from the reclaimed wafer business is applied

Market advantage

By taking advantage of the GRINM group's sales channels, we gain an advantage in Chinese market

Strategic market selection

Focusing on investment in volume zones with a large number of shipments (low to middle end)

Progress

Establish a global quality mass-production line



8 Inch

Production capacity reaches to 130,000 wafers per month

12 Inch

- Completion of flagship plant
- Joint venture with Dezhou Municipal Government Fund
- Production capacity of 60,000 wafers per month

Action Plan



Expand production capacity through capital investment



Strengthen sales promotion activities by taking advantage of customer network in the reclaimed wafer business



Aim for a global market through the use of mergers and acquisitions

^{*(1)} Current: Aiken Semiconductor Silicone Materials Co., Ltd.

Business (5/5 Semiconductor-related equipment and materials Business)



 Manufacture of silicon and quartz consumables for semiconductor manufacturing equipment and sales of scanning acoustic tomograph (SAT), laser diode and electronic components

Business Entity

Manufacturing and sales functions

DG Technologies Co., Ltd.

(subsidiary)

Utilizing precision processing technologies for silicon and quartz Manufacture and sale of consumable materials for semiconductor manufacturing equipment

Overview







Focuses on quartz glass and monocrystalline and polycrystalline silicon products

Action Plan Purchase materials from RST's subsidiary, GRITEK

Cross-selling to Customers for reclaimed wafers

Sell products globally with competitive edge

Trading company functions

- RS Technologies Co., Ltd.
- Union Electronics Solutions Co., Ltd. (subsidiary)

Sales of the latest products on behalf of overseas markets







Laser Diode (Sharp)

Ultrasonic Imaging System (Hitachi)

Expand product lineup

Expand sales area

Expanding sales and customer segment

Summary of Financial Results for FY2023

Summary of Financial Results for FY2023



• Despite the negative impact of the overall semiconductor market, net sales, ordinary income, and net income attributable to owners of the parent increased and increased compared with the plan (million yen)

	FY 2022	FY 2023 Plan	FY 2023	YoY	Compared to FY2023 Plan
Net Sales	49,864	50,800	51,893	+4.1%	+2.2%
Operating Income	13,018	13,100	11,894	△8.6%	△9.2%
Operating Margin	26.1%	25.8%	22.9%	∆3.2 pt	△2.9 pt
Ordinary Income	15,500	14,300	14,921	△3.7%	+4.3%
Ordinary Margin	31.0%	28.2%	28.8%	△2.2 pt	+0.6pt
Net income attributable to owners of parent	7,739	7,400	7,703	△0.5%	+4.1%
EPS (JPY)	299.29	286.18	292.76	∆2.2%	+2.3%

FY 2023 (cumulative) Segment Trends



- Net sales and profit increased year-on-year in the reclaimed wafer business due to customer diversification, portfolio management and increased production through capital investment.
- Net sales decreased year-on-year in the prime wafer business due to deterioration in overall semiconductor market.
- Sales remained strong in the semiconductor equipment and materials business due to enhanced sales capabilities and incorporation of new markets.

(millions of yen)

	Reclaimed Busin		Prime W Marketing E		Semicondo related Equ Materials B	ipment	Other Adju	stments	Total Conso	olidated
		YoY		YoY		YoY		YoY		YoY
Net Sales	20,499	+13.9%	18,736	△17.7%	14,057	+24.8%	△1,399	-	51,893	4.1%
Operating Income	8,114	+11.0%	3,742	△37.6%	882	∆3.5%	△844	-	11,894	△8.6%
Operating Margin	39.6%	△1.0pt	20.0%	△6.3pt	6.3%	△1.8pt	-	-	22.9%	△3.2pt

Financial Results for the Fourth Quarter of FY 2023 (October - December)



•In the fourth quarter, the overall performance was weak due to the deterioration of the semiconductor market.

(million yen)

	FY 2022 4Q	FY 2023 4Q	Year-on-Year	Difference
Net Sales	12,231	12,423	+1.6%	+192
Operating Income	3,239	2,317	△28.5%	△922
Operating Margin	26.4%	18.7%		△7.7pt
Ordinary Income	3,230	2,904	△10.1%	△326
Ordinary Margin	26.4%	23.4%		△3.0pt
Net income attributable to owners of parent	1,949	1,737	△10.9%	△212
EPS (JPY)	¥75.38	¥65.94	△12.4%	∆9.36 yen

Fourth Quarter (October - December) FY2023 Segment Trends



- Net sales and profit increased year-on-year in the Reclaimed Wafer Business due to increasing customer awareness of cost reduction and increased production resulting from capital investment
- Net sales decreased year-on-year in the Prime Wafer Business due to adverse market conditions
- Net sales in the Semiconductor-related equipment & materials Business remained strong due to enhanced sales capabilities and entering into new markets

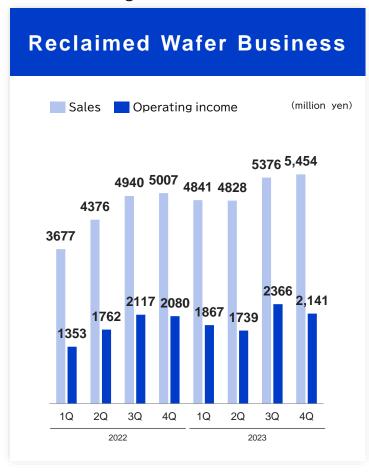
(million yen)

	Reclaimed Waf	er Business	Prime W Marketing E		Semiconductor Materials B		Other adjus	stments	Consolidate	ed total
		YoY		YoY		YoY		YoY		YoY
Sales	5,454	+8.9%	3,515	△29.7%	3,804	+33.8%	△350	-	12,423	+1.6%
Operating Income	2,141	+2.9%	321	△73.0%	45	△83.4%	△189	-	2,318	△28.4%
Operating Margin	39.3%	△2.2pt	9.1%	∆14.7pt	1.2%	△8.3pt	-	-	18.7%	△7.7 pt

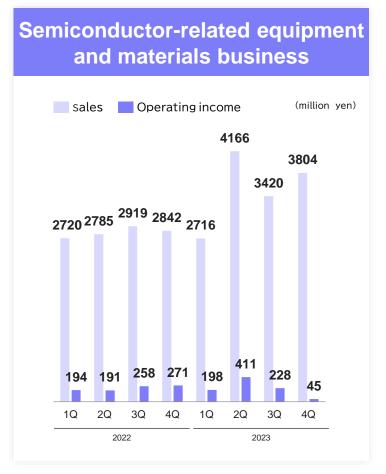
Quarterly Results for the FY2023



- Net sales and operating profit increased year-on-year in the Reclaimed Wafer Business due to increased customer awareness of cost reduction and increased production resulting from capital investment
- Net sales decreased year-on-year in the Prime Wafer Business due to adverse market conditions
- Net sales remained strong in the Semiconductor equipment and materials Business due to enhanced sales capabilities and entering into new markets







Balance Sheet and Cash Flow Statement



•Net assets increased 14 billion yen from the end of the previous fiscal year to 115.4 billion yen (101.4 billion yen in the previous fiscal year).

Consolidated Balance Sheets

(million yen)

		-
	FY 2022	FY 2023
Current Assets	90,470	96,409
Cash and Deposits	67,939	70,758
Notes and accounts receivable-trade	11,651	12,673
Merchandise and finished goods	3,833	6,507
Fixed assets	37,084	44,256
tangible fixed assets	31,285	35,326
intangible fixed assets	270	266
Investments and other assets	5,529	8,663
Total assets	127,554	140,666
Current liabilities	17,622	18,265
Notes and accounts payable	6,466	5,174
Short-term debt	4,694	3,355
non-current debt	8,458	6,973
Long-term debt	3,514	2,092
Total liabilities	26,081	25,238
Net assets	101,473	115,428
Total liabilities and net assets	127,554	140,666

Cash Flow Statement

(million yen)

	Year Ended December 2022	Year Ended December 2023
Cash flows from operating activities	15,316	13,857
Cash flows from investment activities	△1,729	△8,961
Cash flows from financing activities	32,928	△4,801
Effect of Exchange Rate Changes on cash and cash equivalents	△1,412	2,805
Change in cash cash equivalents	45,103	2,900
Cash and cash Cash Equivalents at Beginning of Fiscal Year	21,641	66,744
Cash and Cash Equivalents at End of Fiscal Year	66,744	69,644

Medium-Term Management Plan

Overview of the Medium-Term Management Plan (2024-2026) (Base Plan)



- ➤ While a strong sense of stagnation in the semiconductor market will be still remained in the first half of 2024, sales are expected to exceed 2023 as the recovery trend is expected from the second half of the year.
- •In the reclaimed wafer business, capital investments at 3 sites in Japan, Taiwan, and China to increase production capacity will be carried out.
- •In the prime wafer business, capital investments to increase our market share at 8 inches and 12 inches in China will be executed.
- •In the semiconductor equipment and materials business, entering into new markets and acquiring new customers.

Base Plan*1

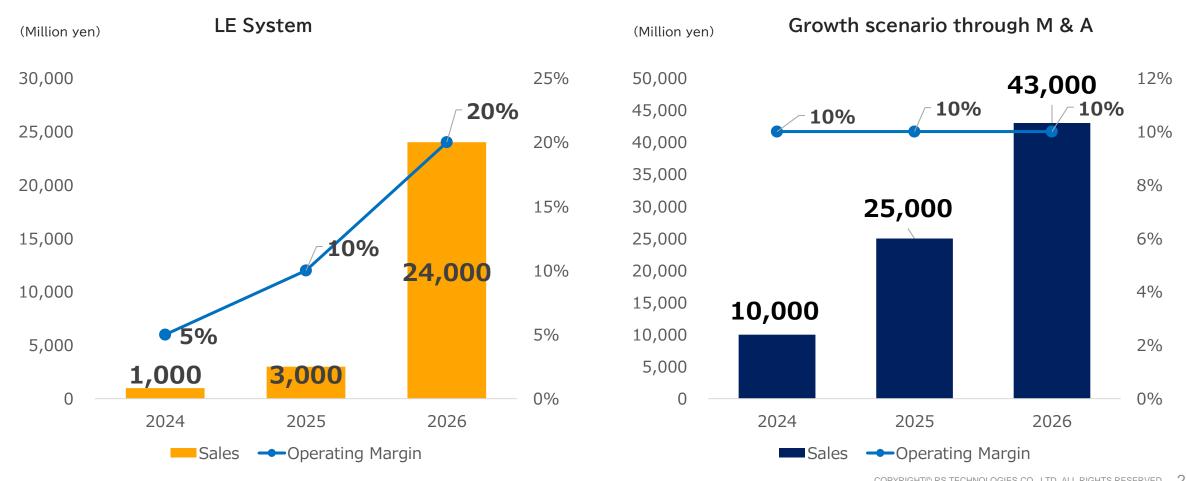
*1: Medium-term
management plan for
three existing businesses
(Reclaimed Wafer
Business, Prime Wafer
Business, and
Semiconductor Equipment
and Materials Business)

(Million Yen)	FY2023	FY2024	FY2025	FY 2026
(1 miloti Teri)	(Actual)			
Net Sales	51,893	54,900	59,300	64,100
growth rate		106%	108%	108%
Operating Income	11,894	14,000	15,330	16,830
%	22.9%	25.5%	25.9%	26.3%
Ordinary Income	14,921	15,400	16,730	18,230
%	28.8%	28.1%	28.2%	28.4%
Net Income	7,703	7,600	8,200	8,800

Overview of the Medium-Term Management Plan (2024-2026) (Upside Plan - Target Value) 1/2



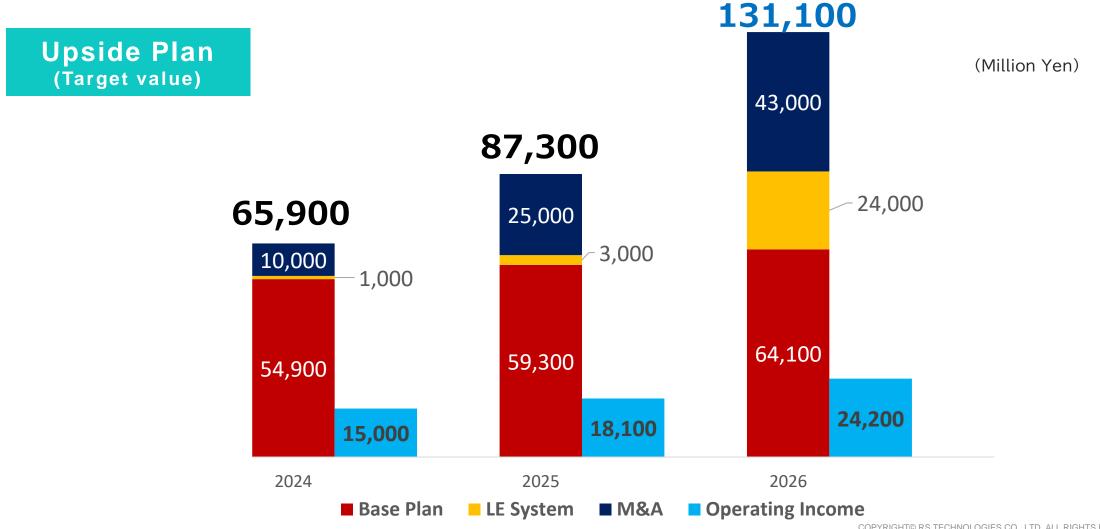
- ♦In addition to the Base Plan, the Upside Plan, which anticipates growth through the LE system and M & A, is also set as a target value
- •The LE system will expand into China, the largest market for vanadium redox flow batteries. Target sales of 24 billion yen and operating margin of 20%
- •Accelerate business expansion by achieving sales of approximately 43 billion yen in 3 years through M & A



Overview of the Medium-Term Management Plan (2024-2026) (Upside Plan - Target Value) 2/2



- •Set a target of approximately 130 billion yen in net sales by 2026 as the Upside Plan (Target Value)
- •Promote scale expansion through LE system and M & A in 3 years of 2024-2026

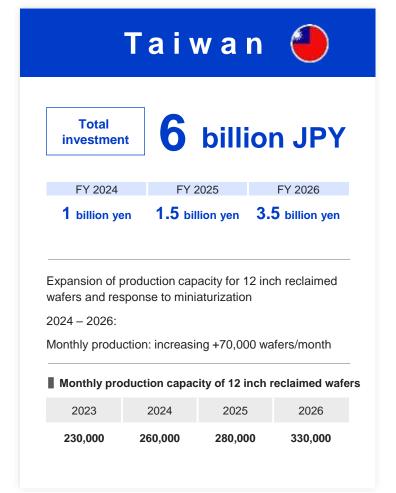


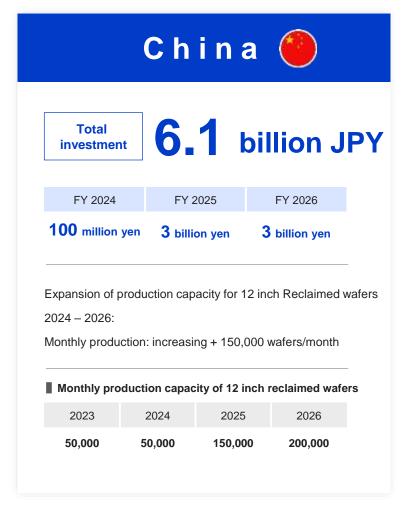
Capital Investment Plan: Reclaimed Wafer Business



- Increasing production capacity in Japan and Taiwan and mass production in Shandong Province, China, to meet strong demand
- Planning production capacity of 890,000 wafers per month by 2026 to meet its demand



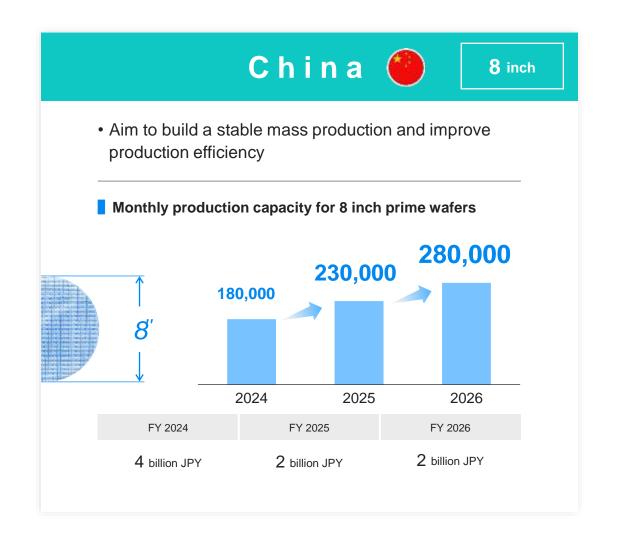


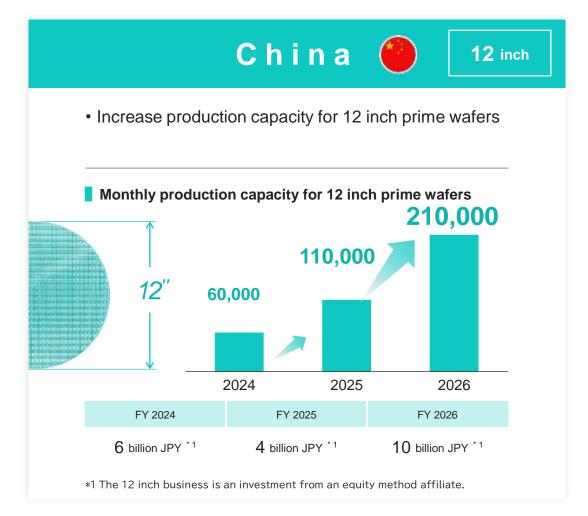


Capital Investment Plan: Prime Wafer Business



- Production of 8 inch prime wafers is expected to increase from 180,000 to 280,000 per month between 2024 and 2026.
- Production of 12 inch prime wafers is expected to increase from 60,000 to 210,000 per month between 2024 and 2026.

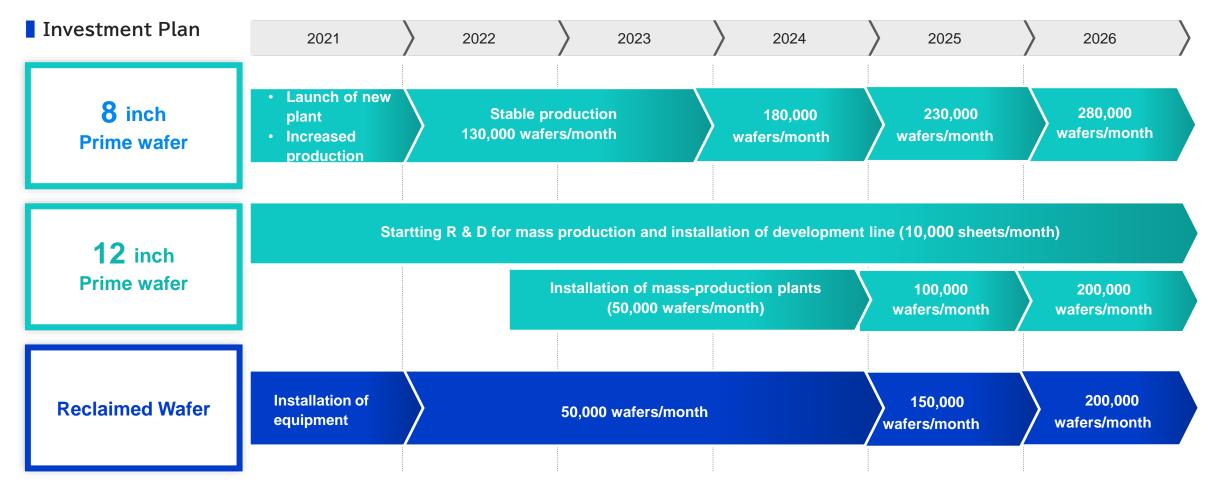




China Investment Plan (Schedule)



- Increase production of 8 inch prime wafers from 130,000 to 180,000 per month
- Set up a mass production line of 12 inch prime wafers, producing 50,000 wafers per month
- Continue mass production of 50,000 reclaimed wafers per month



Demand for Reclaimed Wafers: New 12 inch semiconductor Plants

- In the global market, new 12 inch semiconductor plants are under construction in China, Europe, the United States and Japan.
- RST meets new demand for reclaimed wafers through capital investment in Japan, Taiwan and China.



Regional strategies not to be affected by "Decoupling"

Japan, North America and Europe Sanbongi Factory (Japan's flagship factory) covers mainly North America, Europe and Japan China Taiwan Prime wafers at present Taiwan plant covers Semiconductor foundry companies is sold mainly in China based in in Taiwan

New Business

LE System

New entry into the renewable energy business



In December 2023, LE System Co., Ltd. (100% subsidiary of RST)
 inherited the electrolyte business for vanadium redox flow batteries (VRFB) from the former LE System

Overview of the New Company

🥯 株式会社 LEシステム

Company Name	LE System Co., Ltd.
Establishment	October 13, 2023 (Succession date: December 2023)
Business	Electrolyte production of vanadium redox flow battery
Address	NT Building, 1-47-1 Ohi, Shinagawa-ku, Tokyo, Japan (The same office with RS Technologies, Inc.)
Manufacturing Base	Namie-machi, Fukushima, Japan
Capital	30 million yen
President and CEO	Nagayoshi Ho

- From December 2023, the former LE System business was completely succeeded.
- The key technology of the former LE System is technology originated in Japan, and it has received a lot of support including investment by INCJ, Ltd. (Public and Private Sector Fund in Japan).

Strengths of LE Systems







What is Vanadium Redox Flow Battery (VRFB)?

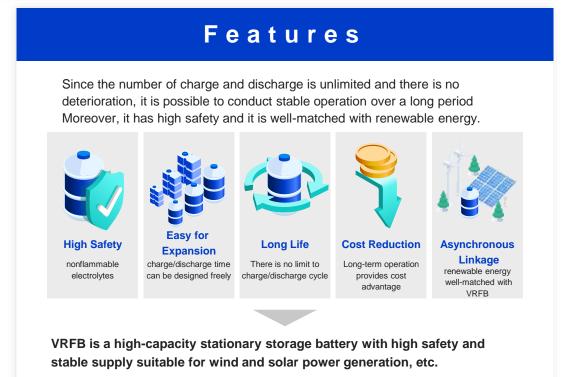


- VRFB is a battery that charges and discharges by circulating and chemically reacting vanadium electrolyte.
- LE system manufactures vanadium electrolyte for VRFB

Primary Use

Use as large-scale, large-capacity stationary storage batteries for wind and solar power generation

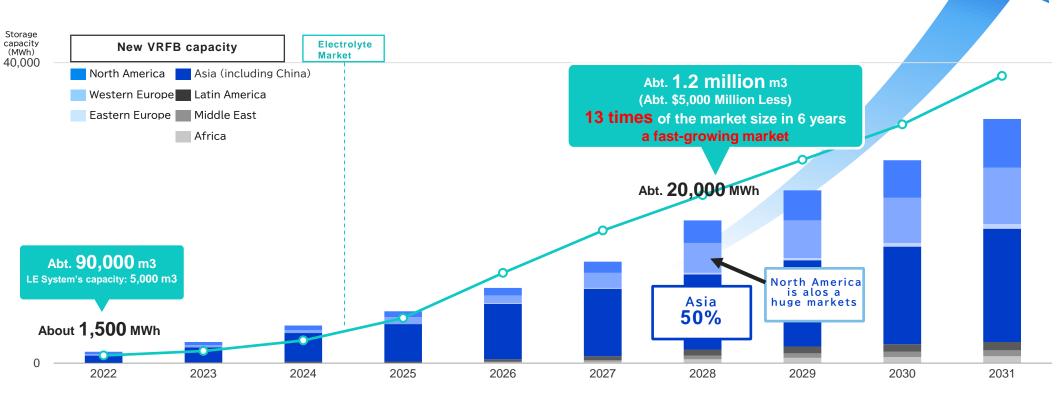
Mechanism VRFB realizes charge and discharge by chemical change (redox) of electrolytic solution, while other batteries charge and discharge by chemical change of electrode. AC/DC converters electrolytic solution **Electrolyte** egative electrode)



Market Size of Vanadium Redox Flow Battery (VRFB)



- The VRFB market is expected to expand more than 10 times in 2028. Demand for electrolytes is expected to increase.
- New VRFB Capacity and Electrolyte Market Forecast



- LE System will take advantage of RST's overseas network (especially its strengths in Asia, including China).
- Aiming to achieve top global market share by 2028

RST's Intent to incorporate LE system and LE System's growth strategy



- •LE system, established in October 2023, manufactures electrolytes for vanadium redox flow batteries (VRFB).
- In 2024, LE Sytem began sales activities globally to expand their business.

Intent to incorporate LE System

- "Revitalization" has been a key word for RST's business growth since the establishement of RST
- LE System owns the business model which conforms to RST's "Revitalization" and is expected to grow in the future.
 - 1) Expect rapid growth in the renewable energy sector
 - 2) Possess technology to produce vanadium electrolyte by recycling residues generated at oil plnats
 - 3) Electrolyte itself can be recycled

Future Growth Strategy

- China has adopted VRFB as its national policy next to lithium-ion batteries, and China will become its largest market.
- Leverage the cost competitiveness of the LE system's proprietary technology and RST's business base in China to achieve the top share of the VRFB market in China.
- Continue to invest in Japan as a research and development base
- Establish a system capable of mass production in Japan when the need for large-capacity stationary storage batteries grows in Japan

Appendix

Strengths of Nagayoshi Ho

- President and CEO, Nagayoshi Ho has used the knowledge accumulated in Japan for more than 20 years. His strength includes
 ability to sell, network, partner and fund globally
- He has assembled a team of professionals from a broad range of fields, including advanced technology and finance.



Nagayoshi Ho

- · Born in 1970 in Fujian Province, China
- Josai International University: Ph.D in Business Administration
- 1998: He established Eiki Shoji Co.,Ltd
- 2010: He established RS Technologies Co.,Ltd
- Naturalized in Japan in 2014

Specialty

M & A. Business Alliance

Favorite Maxim

Where there is a will, there is a way

Note

- He came to Japan after graduating from high school. He has invested in various industries such as fund, trade, hotel, IT, and agriculture in addition to semiconductor business.
- Based on his belief that "Japan's manufacturing is the best in the world," he has been traveling around the world to spread his belief.

Sanbongi Plant (RS Technologies, Reclaimed Wafer Business)



- Jan. 2011: Started operations of Sanbongi Factory Plant
- Jun. 2015: Started production at Plant 8 with state-of-the-art facilities





Company name	RS Technologies, Co.,Ltd.
Establishment	December 2010
Product	5, 6, 8, 12 inch Reclaimed Wafer
Production capacity	8 inch : 150,000 wafers per month 12 inch : 310,000 wafers per month
Address	Osaki City, Miyagi Prefecture, Japan
Certification	ISO9001, ISO14001

Taiwan Plant (RSTW, Reclaimed Wafer Business)



• Dec. 2015: Production commenced at RSTEC Semiconductor Taiwan Co., Ltd. (RSTW).





Company name	RSTEC Semiconductor Taiwan Co., Ltd
Establishment	December 2015
Product	12 inch Reclaimed Wafer
Production capacity	12 inch: 230,000 wafers per month
Address	Tainan, Taiwan
Certification	ISO9001, ISO14001

Dezhou Plant (Shandong GRITEK, 8-inch Prime Wafer Business)



- Aug. 2018: Shandong GRITEK Co., LtdShandong GRITEK, a consolidated subsidiary of GRITEK) was established.
- Oct. 2020: The Dezhou plant started prime wafer production.





Company name	Shandong GRITEK Co., Ltd.
Establishment	October 2020
Product	5,6,8 inch Prime Wafer
Production capacity	5 inch: 50,000 wafers per month 6 inch: 200,000 wafers per month 8 inch: 130,000 wafers per month
Address	Dezhou city, Shandong, China
Certification	ISO9001, ISO14001

SGRS Research and Development Center (SGRS, 12 inch Prime Wafer Business)



- Mar. 2020, GRINM RS Semiconductor Materials Co., Ltd. (SGRS) was established.
- In 2021, R&D line for 12 inch prime wafer (10,000 wafers per month) was established.





Company name	GRINM RS Semiconductor Materials Co., Ltd.
Establishment	March 2020
Products	 12 inch Prime Wafer 12 inch Reclaimed Wafer
Production capacity	 50,000 wafers per month 10,000 wafers per month (R&D line) 50,000 wafers per month
Address	-Dezhou, Shandong, China -Beijing, China

Namie Plant (LE System, Renewable Energy Business)



- In December 2023, RST completely succeeded the electrolyte manufacturing business *1 of the former LE System.
- *(1) The key technology of the former LE System is technology that originated in Japan, and has received a lot of support including investment by INCJ Co., Ltd. (Public and Private Sector Fund in Japan).





Company name	LE System Co., Ltd.
Establishment	October 13, 2023 (Business Succession Date: December 2023)
Business Profile	Electrolyte for vanadium redox flow batteries
Production capacity	5,000m3 per year
Location	Namie-machi, Fukushima Prefecture (Plant) Tsukuba City, Ibaraki Prefecture (office)

Kamisu Plant (DG Technologies, Semiconductor-related equipment and materials Business)



- In January 2019, DG Technologies became a consolidated subsidiary of RS Technologies.
- To meet growing demand, DG Technologies increases production through capital investment and the improvement of productivity.





Company Name	DG Technologies Co., Ltd.
Establishment	October 1981
Product	For dry etching equipment Consumable member made of quartz and silicon
Address	Kamisu City, Ibaraki Prefecture
Certification	ISO9001

Kurihara Plant (DG Technologies, Semiconductor-related equipment and materials business)

- In May 2021, the Kurihara Plant was set up in Miyagi Prefecture.
- The Kamisu Plant and the Kurihara Plant were established as two production bases to meet increasing orders.

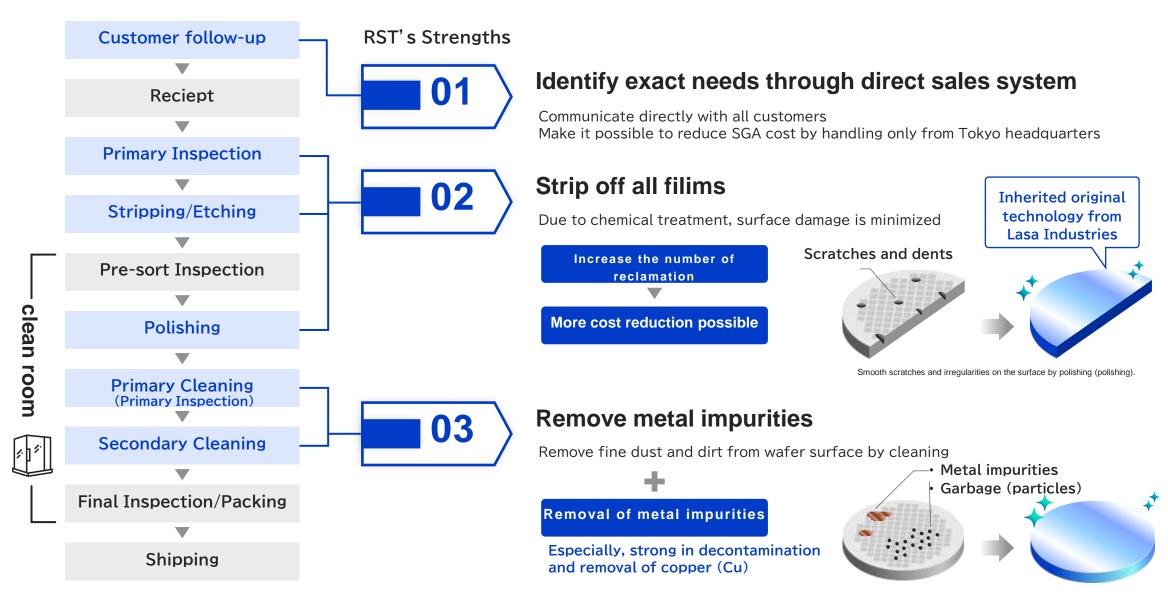




Company Name	DG Technologies Co., Ltd.
Commencement of operation	May 2021
Product	For dry etching equipment Consumable member made of quartz and silicon
Address	Kurihara City, Miyagi Prefecture
Building area	5,000m2

Reclaimed Wafer Business (1)



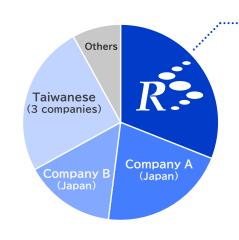


Reclaimed Wafer Business (2)



Increasing market share in the reclaimed wafer

Market share in the 12 inch regeneration market



RS Technologies

Due to the new construction and expansion of Sanbongi in Taiwan, production capacity increased, and the current market share rose to about 33%.

By further increasing production capacity through existing facilities at both factories, using an empty factory in Sanbongi, and using business tieups and M & As, etc.

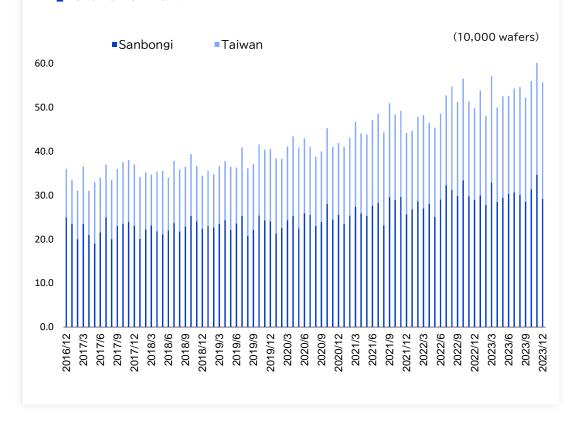
RST aims to increase market share.

Year	Second half of 2015	2016	2017	2018	2019	2020	2021	2022	2023	
RST capacity	240k	280k	300k	340k	400k	420k	460k	550k	590k	
Market Share	24%	29%	30%	31%	33%	33%	33%	33%	33%	

Estimated in our company based on SEMI data

Shipments at the Sanbongi Plant and Taiwan Plant

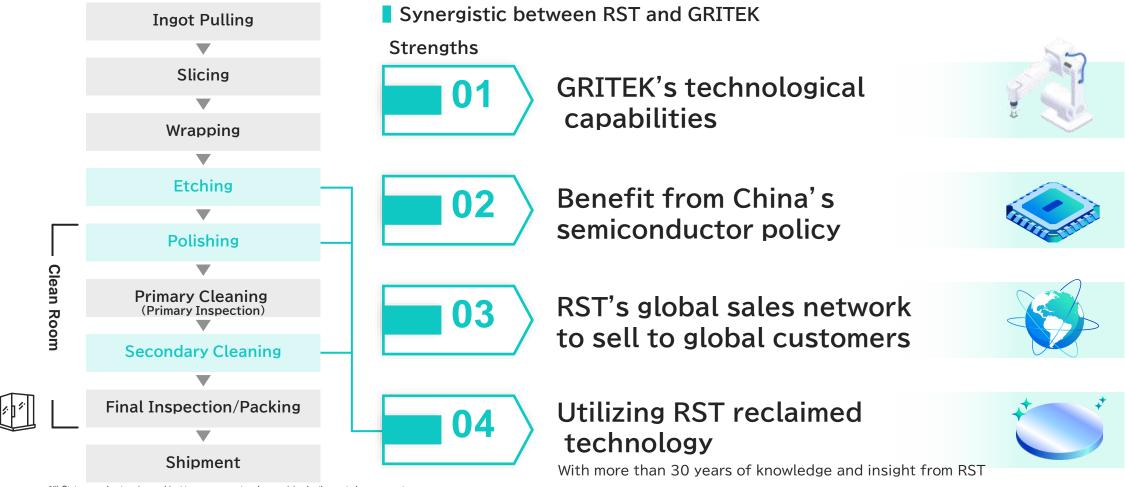
Trends in the number of 12 inch wafers shipped at the Sanbongi Plant and Taiwan Plant



Expansion into the Prime Wafer business



• With a Chinese central company *1, GRINM, GRINM Semiconductor Material Co., Ltd (GRITEK) was established.



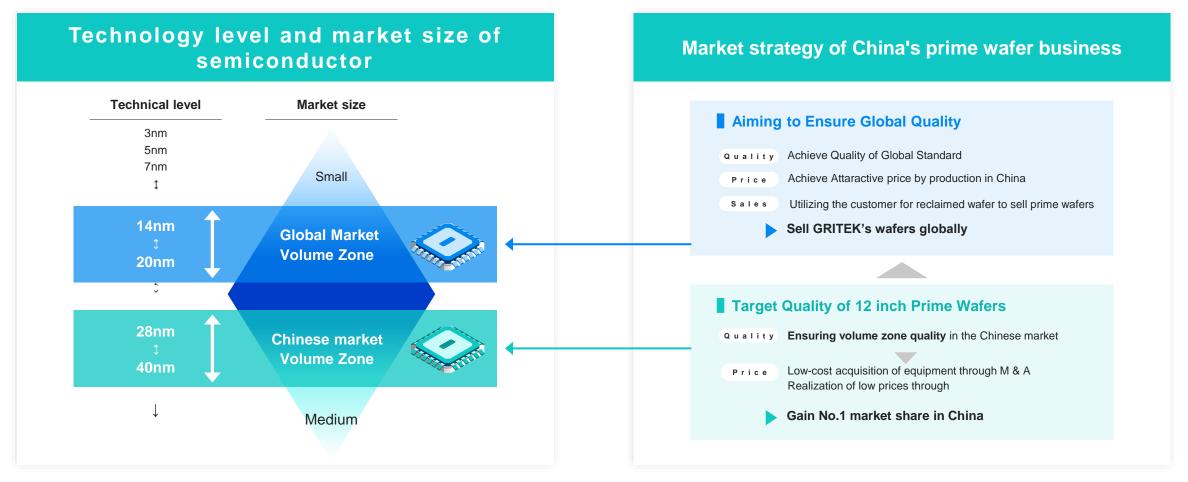
^{*(}i) State-owned enterprises subject to management and supervision by the central government

^{*(}ii) Current status: Riken Semiconductor Silicone Material Co., Ltd.

China 12 inch prime wafer market strategy



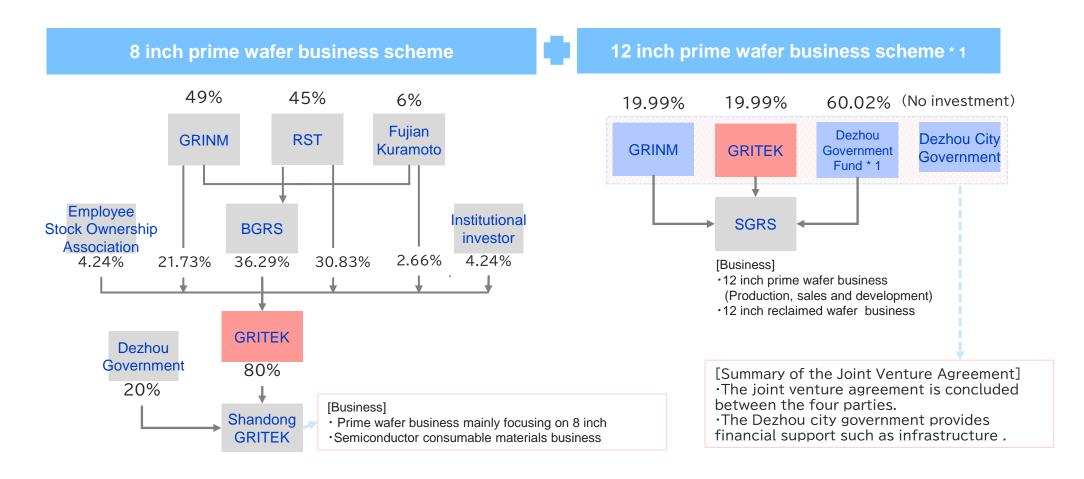
- Targeting No.1 share in Chinese market by securing volume zone quality in Chinese market
- After achieving No.1 share in Chinese market, next step will be to become a prime wafer manufacturer who is able to provide products with global standard quality to global semiconductor manufacturers



Business scheme to invest in the prime wafer business



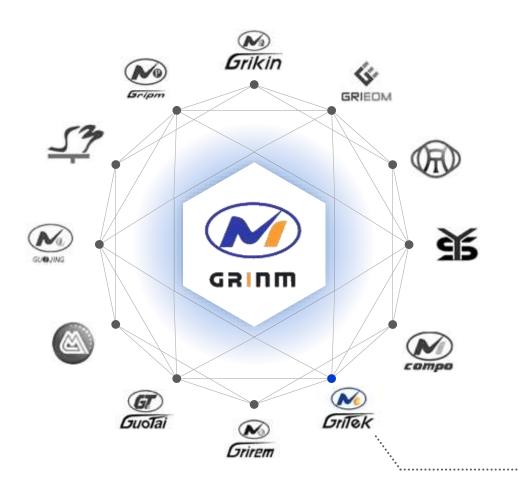
- GRITEK is listed on the Shanghai Stock Exchange, STAR Market (SHA: 688432).
- The below risk-controlled model involving a Chinese sovereign wealth funds



X1 Dezhou Huida Semiconductor Equity Investment Fund Partnership

About Joint Venture Partner (GRINM)





Established in 1952

largest state-owned research institute in the field of nonferrous metals in China

About 2,000 researchers out of about 4,100 employees

460,000 state-owned companies out of about 45 million companies in China and out of 460,000 companies,

98 central companies exist and GRINM is one of them

a research institute integrating government, industry, and academia. Policies in the metal field are communicated through GRINM

GRINM established operating companies that serve as evidence of its successful research. Currently, 4 research institutes and 30 operating companies exist

GRITEK, a consolidated subsidiary of RST, was established as <u>GRINM's first operating company</u> and listed on the Shanghai Stock Exchange.

RS Technologies's Targeting Business Portofolio

Growth **Business Expansion** Expanding RST's business and its sales areas

			Japan	China	Asia (other than China)	Europe and America
	Reclaimed wafer					•
	Diagram	12inch				
Manufacturing	Prime wafer	8inch, etc.	O	•	•	
	Consumables related to manufacturing	semiconductor	0	•	•	•
	semiconductor manufac	turing		0		
"renewable /recycled/	New Business				0	0
revititalized" business	Vanadium Redox Flow	Battery	0	O	0	0
E contract	Manufacturing Equipme	nt	0	•	•	•
Function of Trading	Semiconductors, Electro	onic Components,	0	•	•	0
Company	Others (solar, etc.)		0		•	0

Region

Planned Regional expansion

Year by Year Results



(millions yen)	2013	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023
Sales	3,475	4,566	5,285	8,864	10,932	25,478	24,501	25,561	34,620	49,864	51,893
Gross profit	1,173	1,820	1,852	2,544	4,252	8,366	7,940	8,681	11,870	18,432	17,413
SG & A expenses	471	654	791	958	1,269	2,615	3,223	4,151	4,995	5,413	5,519
Operating income	703	1,166	1,061	1,585	2,982	5,751	4,717	4,530	6,874	13,018	11,894
Ordinary income	819	1,247	770	1,444	3,159	6,141	5,416	5,252	8,832	15,500	14,921
Net income (* 1)	525	664	143	861	2,113	3,620	3,035	2,824	3,303	7,739	7,703
Dividends (yen) (* 2)	-	-	-	10	5	10	15	20	25	35	30
Capital investment	338	3,503	4,665	209	95	1,328	4,809	12,409	7,827	5,379	5,999
Depreciation	87	103	326	682	714	1,298	1,814	1,674	2,942	3,498	3,774
R&D expenses	1	6	11	85	183	501	449	929	1,308	1,657	1,764
Number of employees	152	191	265	373	434	1,159	1,277	1,187	1,333	1,533	1,534

^(* 1) Net income attributable to owners of the parent (* 2) Dividends for FY2023 are shown after the split (1/2) on January 1, 2023.

Principal financial statements



(million yen)	2013	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023
Assets											
Current Assets	1,811	2,759	3,732	5,348	7,388	26,074	32,760	32,626	45,804	90,470	96,409
Cash and deposits	397	1,190	1,842	1,952	3,243	14,879	22,156	19,082	25,438	67,939	70,758
Notes and accounts receivable-trade	681	696	795	2,531	2,916	6,958	6,047	6,321	9,517	11,651	12,673
Goods and products	396	376	361	348	446	1,343	1,713	2,116	2,783	3,833	6,507
Non-current Assets	508	4,064	5,845	5,333	4,843	10,516	15,873	26,124	33,206	37,084	44,256
Property, factory, and equipment assets	461	3,918	5,667	5,152	4,674	8,963	14,635	24,146	29,023	31,285	35,326
Intangible fixed assets	19	15	29	23	19	1,099	732	527	417	270	266
Investments and other assets	27	130	148	158	149	453	506	1,451	3,766	5,529	8,663
Total assets	2,320	6,823	9,577	10,682	12,231	36,591	48,634	58,750	79,010	127,554	140,666
Liabilities											
Current Liabilities	960	2,292	2,295	2,993	3,370	4,979	7,252	12,631	14,171	17,622	18,265
Notes and accounts payable	138	151	186	283	398	1,554	1,614	2,871	4,317	6,466	5,174
interest-bearing debt	136	827	1,216	1,538	1,276	976	1,730	1,522	3,020	4,694	3,355
Non-current Liabilities	709	2,934	4,798	4,317	3,335	2,474	5,400	5,754	9,827	8,458	6,973
Long-term loans payable	615	2,925	4,079	3,620	2,767	1,848	2,232	1,613	5,097	3,514	2,092
Total Liabilities	1,670	5,227	7,093	7,310	6,705	7,453	12,652	18,385	23,999	26,081	25,238
Net assets											
Net assets	649	1,596	2,483	3,371	5,526	29,137	35,981	40,365	55,011	101,473	115,428
Total liabilities and net assets	2,320	6,823	9,577	10,682	12,231	36,591	48,634	58,750	79,010	127,554	140,666

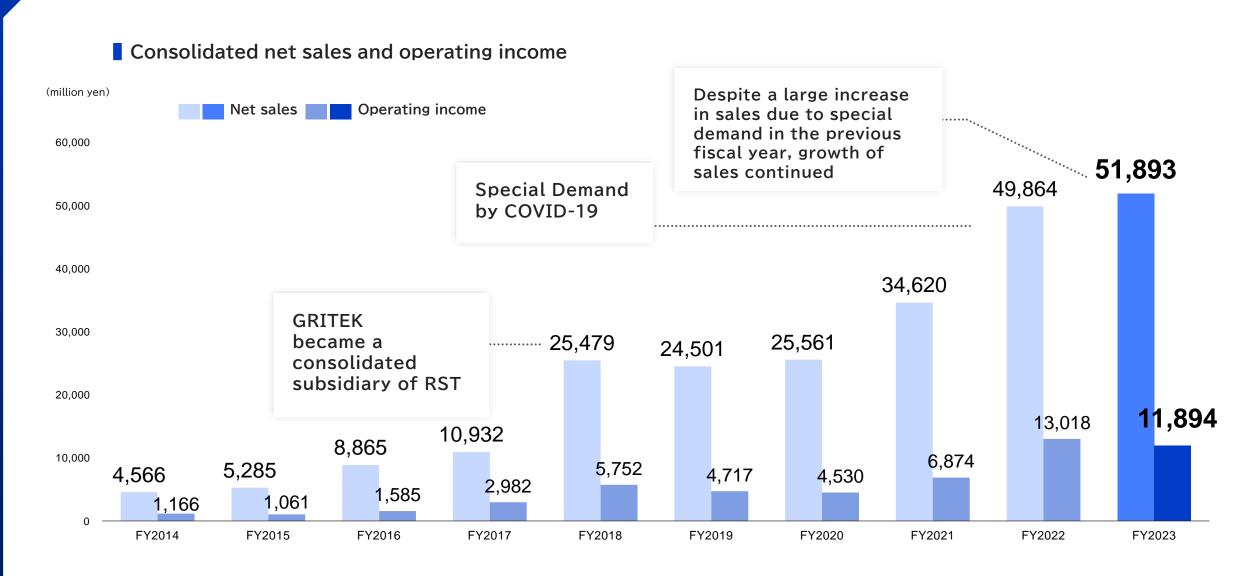
Performance by Segment



(million yen)	2013	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023	
Sales												
Reclaimed Wafer Business	3,347	4,414	5,107	7,144	9,487	10,973	10,776	11,461	12,717	18,001	20,499	
Prime Wafer Business	-	-	-	-	-	11,918	10,058	8,755	14,780	22,752	18,736	
Semiconductor-related equipment and material Business	-	-	-	1,654	1,393	2,918	4,047	6,272	8,450	11,265	14,057	
Other adjustments	127	151	178	66	52	△331	△380	△927	△1,327	△2,154	△1,399	
Segment profit		·	·		·		·	·	·			
Reclaimed Wafer Business	916	1,444	1,377	1,765	3,396	4,011	4,081	4,027	4,731	7,312	8,114	
Prime Wafer Business	-	-	-	-	-	2,048	1,503	1,041	2,539	5,995	3,742	
Semiconductor-related equipment and material Business	-	-	-	230	130	366	171	211	382	914	882	
Other adjustments	△214	△278	△316	△409	△543	△675	△1,038	△749	△778	△1,203	△844	
segment assets												
Reclaimed Wafer Business	1,337	5,040	6,987	5,657	8,120	9,150	10,336	11,698	14,302	18,530	21,833	
Prime Wafer Business	-	-	-	-	-	21,313	29,311	35,697	53,202	95,788	100,768	
Semiconductor-related equipment and material Business	-	-	-	1,137	1,305	1,939	3,179	5,387	7,310	6,801	8,775	
Other adjustments	982	1,783	2,589	3,887	2,805	4,315	5,806	5,968	4,243	6,435	9,290	

Consolidated Financial Results







The content of these materials was prepared based on generally recognized economic potential and certain assumptions considered reasonable by the Company but is subject to revision without notice due to changes in various business environments affecting management.

Materials and information provided for this announcement contain forward-looking statements. This information is based on assumptions pertaining to the current outlook, forecasts and risks, and contains uncertainties that could result in different outcomes.

Even in the case of new information, future events, or other relevant matters, the Company is under no obligation to update or revise the forward-looking statements contained in this material.